The Institute for Interconnecting and Packaging Electronic Circuits
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IPC-TM-650
TEST METHODS MANUAL

Number	
2.4.1.3	
Subject	
Adhesion, Resistors (Hybrid Circuits)	
Date	Revision
12/87	
Originating Task Group	
N/A	

1.0 Scope This test method is to determine the adhesion quality of resistive and capacitive materials on the substrate surface of finished hybrid circuits.

2.0 Applicable Documents General Service Administration approved Commercial Item Description (CID) Standard AA113B, ''Tape Pressure Sensitive Adhesive'', FSC 7510-551-982.

3.0 Test Specimen

3.1 Any finished hybrid circuit having the resistor under test applied to its surface. A minimum of three tests should be performed for each evaluation.

4.0 Apparatus

4.1 Tape 12.7 mm [1/2 inch] wide roll pressure sensitive tape (3m brand 600 transparent tape or equivalent per CID - AA113B Type 1; Class B)

5.0 Procedure

5.1 Test

5.1.1 Press a strip of pressure sensitive tape 12.7 mm [1/2 inch] wide and 2 inches long firmly across the surface of the board covering marking on both the laminate and metal conductors.

5.1.2 Rapidly move the tape by manual force applied approximately perpendicular to the markings and board surface. Fresh tape must be used each time.

5.2 Evaluation

5.2.1 Visually examine the tape and specimen for evidence of any portion of the resistor having come off the surface of the hybrid circuit as evidenced by particles of resistors adhering to the tape.

6.0 *Note*

6.1 Failure of the resistive material to properly adhere to the ceramic substrate constitutes failure of the test.